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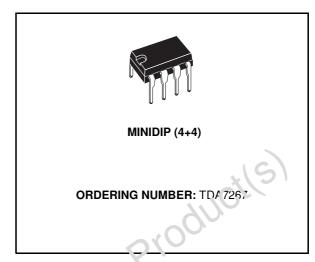
2W MONO AMPLIFIER

- CAN DELIVER 2W THD 10% 12V/8Ω
- INTERNAL FIXED GAIN 32dB
- NO FEEDBACK CAPACITOR
- NO BOUCHEROT CELL
- THERMAL PROTECTION
- AC SHORT CIRCUIT PROTECTION
- SVR CAPACITOR FOR BETTER RIPPLE REJECTION
- LOW TURN-ON/OFF POP
- STAND-BY MODE

DESCRIPTION

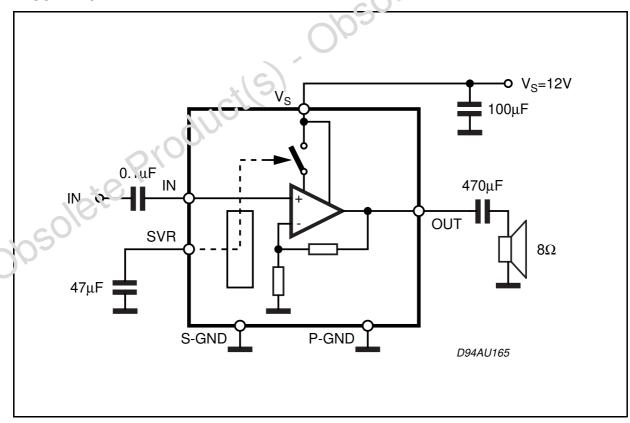
The device TDA7267 is a new technology Mono Audio Amplifier in MINIDIP package specifically designed for TV application.

Thanks to the fully complementary output configu-



ration the device delivers a rail to rail voltage swing without need of boostrap capacitors.

BLOCK DIAGRAM

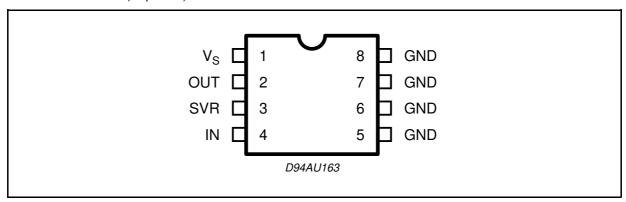


June1998 1/5

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V_S	Operating Supply Voltage	18	٧
lo	Output Put Peak Current	1.5	Α
T _{op}	Operating Temperature Range	0 to 70	°C
Tj	Junction Temperature	150	°C
T _{stg}	Storage Temperature Range	-40 to 125	°C

PIN CONNECTION (Top view)



THERMAL DATA

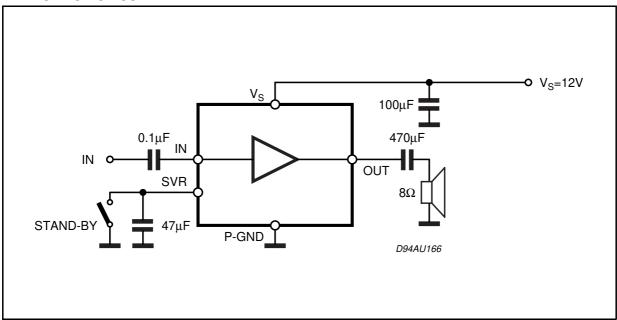
Symbol	Parameter		Unit
R _{th j-amb}	Thermal Resistance Junction to ambient (on PCB)	80	°C/W
R _{th j-case}	Thermal Resistance Junction to case	15	°C/W

ELECTRICAL CHARACTERISTICS ($T_{amb} = 25^{\circ}C$; $V_S = 12V$; $R_L = 8\Omega$; f = 1KHz; unless otherwise specified.)

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Unit
Vs	Supply Voltage Range		4.5		18	V
Is	Quiescent Current			20	30	mA
I _{sb}	Stand-By Current	Pin 3 shorted to GND			0.3	mA
Vo	Quiescent Output Voltage			6		V
A _V	Voltage Gain			32		dB
R _{IN}	Input Impedance			100		ΚΩ
Po	Output Power	THD = 10%	1.8	2		W
THD	Distortion	P _O = 1W			1.0	%
SVR	Supply Voltage Rejection	V _{ripple} = 150mVrms; F _{ripple} = 1KHz		50		dB
Eı	Input Noise Voltage	Rg = $10K\Omega$; BW = $20Hz$ to $20KHz$		1.5	5	μV
V_{sb}	Stand-By Enable Voltage		•		1	V

2/5

APPLICATION CIRCUIT



APPLICATION HINTS:

For 12V supply and 8Ω speaker application, its maximum power dissipation is about 1W.

Assumming that max ambient temperature is 70° C. Required thermal resistance of the device and heat dissipating means must be equal to $(150 - 70)/1 = 80^{\circ}$ C/W.

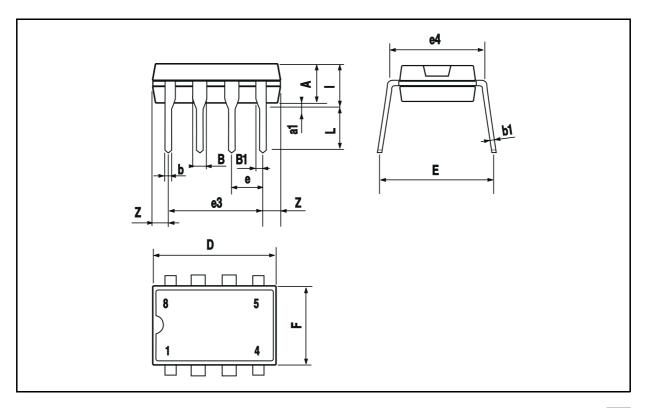
Junction to pin thermal resistance of the package is about 15°C/W. That means external heat sink of about 65°C/W is required.

Cu ground plane of PCB can be used as heat dissipating means.

Stand-By switches must be able to discharge $C_{\mbox{\scriptsize svr}}$ current.

MINIDIP PACKAGE MECHANICAL DATA

DIM.	mm			inch			
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	
Α		3.3			0.130		
a1	0.7			0.028			
В	1.39		1.65	0.055		0.065	
B1	0.91		1.04	0.036		0.041	
b		0.5			0.020		
b1	0.38		0.5	0.015		0.020	
D			9.8			0.386	
E		8.8			0.346		
е		2.54			0.100		
e3		7.62			0.300		
e4		7.62			0.300		
F			7.1			0.280	
I			4.8			0.189	
L		3.3			0.130		
Z	0.44		1.6	0.017		0.063	



4/5

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